



L	Hits	Search Text	DB	Time stamp
Number				
2	0	(pcb or (printed with circuit)) and	USPAT;	2003/08/14
		((phosphor with bronze with nickel with	US-PGPUB;	15:30
		spring with gold with (contact or	EPO; JPO;	1
		contacting)) same (housing or connector)	DERWENT;	
		same (solder or solder\$))	IBM TDB	
3	0	(pcb or (printed with circuit)) and	USPAT;	2003/08/14
		((phosphor with bronze with nickel with	US-PGPUB;	15:31
		spring with gold with (contact or	EPO; JPO;	
		contacting)) same (housing or connector)	DERWENT;	
		same (solder or solder\$))	IBM TDB	
4	6	(pcb or (printed with circuit)) and	USPAT;	2003/08/14
		((phosphor with bronze with nickel with	US-PGPUB;	15:37
		gold with (contact or contacting)) same	EPO; JPO;	-3131
		(housing or connector) same (solder or	DERWENT;	
		solder\$))	IBM TDB	
5	0	(pcb or (printed with circuit)) and	USPAT;	2003/08/14
	-	((phosphor with bronze with nickel with	US-PGPUB;	15:38
		gold with (contact or contacting)) same	EPO; JPO;	10.00
		((housing or connector) with (opening or	DERWENT;	1
		hole)) same (solder or solder\$))	IBM TDB	
6	1	(pcb or (printed with circuit)) and	USPAT;	2003/08/14
1	-	((phosphor same bronze same nickel same	US-PGPUB;	15:39
		gold same (contact or contacting)) same	EPO; JPO;	13.33
		((housing or connector) with (opening or	DERWENT;	
		hole)) same (solder or solder\$))	IBM TDB	
7	9	(pcb or (printed with circuit)) and	USPAT;	2003/08/14
'		((phosphor same bronze same nickel same	US-PGPUB;	15:44
		gold same (contact or contacting)) same	EPO; JPO;	13.44
		((housing or connector)) same (solder or	DERWENT;	
		solder\$))	IBM TDB	
8	1	347/\$.ccls. and (pcb or (printed with	USPAT;	2003/08/14
·	-	circuit)) and ((phosphor same bronze same	US-PGPUB;	15:44
		nickel same gold same (contact or	EPO; JPO;	15.44
		contacting)) same ((housing or	DERWENT;	
j		connector)) same (solder or solder\$))	IBM TDB	
9	2	347/\$.ccls. and (pcb or (printed with	USPAT;	2003/08/14
1	2		US-PGPUB;	15:45
		circuit)) and ((phosphor and bronze and nickel and gold and (contact or		13:45
		contacting)) and ((housing or connector))	EPO; JPO;	1
			DERWENT;	
		and (solder or solder\$))	IBM TDB	